



Am29LV160D

16 Megabit (2 M x 8-Bit/1 M x 16-Bit)

CMOS 3.0 Volt-only Boot Sector Flash Memory

DISTINCTIVE CHARACTERISTICS

■ Single power supply operation

- Full voltage range: 2.7 to 3.6 volt read and write operations for battery-powered applications
- Regulated voltage range: 3.0 to 3.6 volt read and write operations and for compatibility with high performance 3.3 volt microprocessors

■ Manufactured on 0.23 μm process technology

- Fully compatible with 0.32 μm Am29LV160B device

■ High performance

- Access times as fast as 70 ns

■ Ultra low power consumption (typical values at 5 MHz)

- 200 nA Automatic Sleep mode current
- 200 nA standby mode current
- 9 mA read current
- 20 mA program/erase current

■ Flexible sector architecture

- One 16 Kbyte, two 8 Kbyte, one 32 Kbyte, and thirty-one 64 Kbyte sectors (byte mode)
- One 8 Kword, two 4 Kword, one 16 Kword, and thirty-one 32 Kword sectors (word mode)
- Supports full chip erase
- Sector Protection features:
 - A hardware method of locking a sector to prevent any program or erase operations within that sector
 - Sectors can be locked in-system or via programming equipment
 - Temporary Sector Unprotect feature allows code changes in previously locked sectors

■ Unlock Bypass Program Command

- Reduces overall programming time when issuing multiple program command sequences

■ Top or bottom boot block configurations available

■ Embedded Algorithms

- Embedded Erase algorithm automatically preprograms and erases the entire chip or any combination of designated sectors
- Embedded Program algorithm automatically writes and verifies data at specified addresses

■ Minimum 1,000,000 write cycle guarantee per sector

■ 20-year data retention at 125°C

- Reliable operation for the life of the system

■ Package option

- 48-ball FBGA
- 48-pin TSOP
- 44-pin SO

■ CFI (Common Flash Interface) compliant

- Provides device-specific information to the system, allowing host software to easily reconfigure for different Flash devices

■ Compatibility with JEDEC standards

- Pinout and software compatible with single-power supply Flash
- Superior inadvertent write protection

■ Data# Polling and toggle bits

- Provides a software method of detecting program or erase operation completion

■ Ready/Busy# pin (RY/BY#)

- Provides a hardware method of detecting program or erase cycle completion (not available on 44-pin SO)

■ Erase Suspend/Erase Resume

- Suspends an erase operation to read data from, or program data to, a sector that is not being erased, then resumes the erase operation

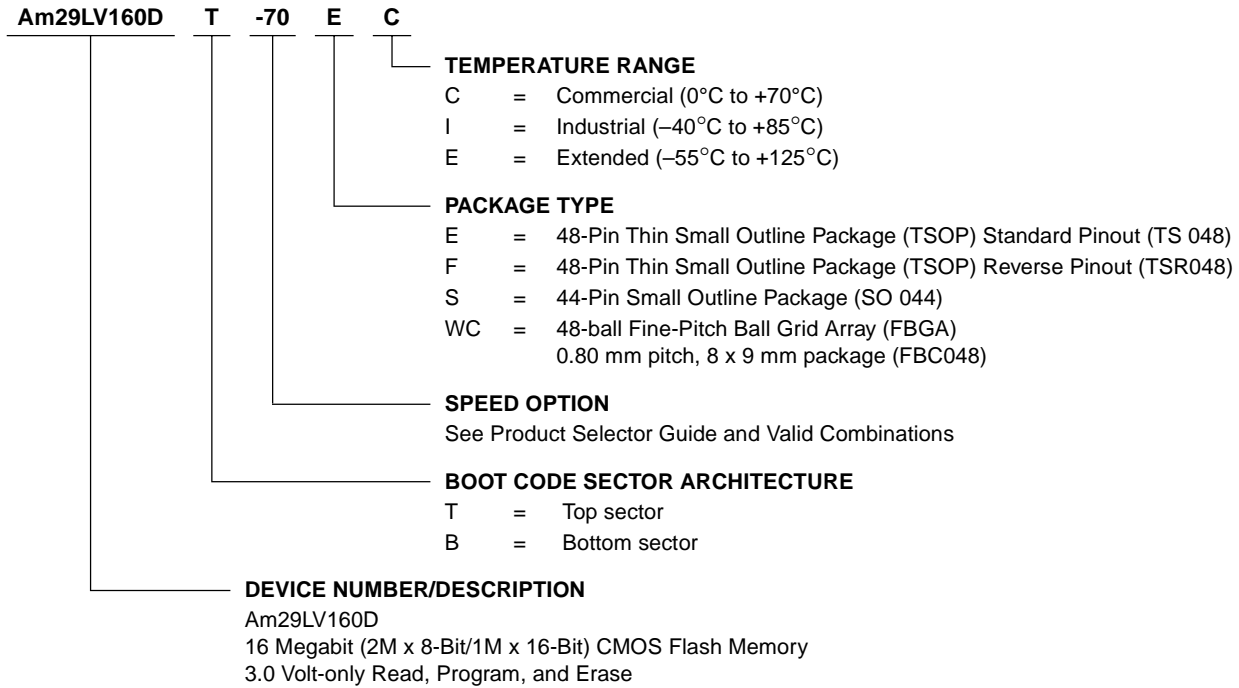
■ Hardware reset pin (RESET#)

- Hardware method to reset the device to reading array data

ORDERING INFORMATION

Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of the elements below.



Valid Combinations For TSOP and SO Packages	
Am29LV160DT-70, Am29LV160DB-70	EC, EI, EE, FC, FI, FE, SC, SI, SE
Am29LV160DT-90, Am29LV160DB-90	
Am29LV160DT-120, Am29LV160DB-120	

Valid Combinations for FBGA Packages			
Order Number		Package Marking	
Am29LV160DT-70, Am29LV160DB-70	WCC, WCI, WCE	L160DT70V, L160DB70V	C, I, E
Am29LV160DT-90, Am29LV160DB-90		L160DT90V, L160DB90V	
Am29LV160DT-120, Am29LV160DB-120		L160DT12V, L160DB12V	

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature
 Plastic Packages -65°C to +150°C
 Ambient Temperature
 with Power Applied. -65°C to +125°C
 Voltage with Respect to Ground
 V_{CC} (Note 1) -0.5 V to +4.0 V
 A9, OE#, and RESET# (Note 2) . . -0.5 V to +12.5 V
 All other pins (Note 1) -0.5 V to $V_{CC}+0.5$ V
 Output Short Circuit Current (Note 3) 200 mA

Notes:

1. Minimum DC voltage on input or I/O pins is -0.5 V. During voltage transitions, input or I/O pins may overshoot V_{SS} to -2.0 V for periods of up to 20 ns. See Figure 7. Maximum DC voltage on input or I/O pins is $V_{CC} + 0.5$ V. During voltage transitions, input or I/O pins may overshoot to $V_{CC} + 2.0$ V for periods up to 20 ns. See Figure 8.
2. Minimum DC input voltage on pins A9, OE#, and RESET# is -0.5 V. During voltage transitions, A9, OE#, and RESET# may overshoot V_{SS} to -2.0 V for periods of up to 20 ns. See Figure 7. Maximum DC input voltage on pin A9 is +12.5 V which may overshoot to 14.0 V for periods up to 20 ns.
3. No more than one output may be shorted to ground at a time. Duration of the short circuit should not be greater than one second.

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this data sheet is not implied. Exposure of the device to absolute maximum rating conditions for extended periods may affect device reliability.

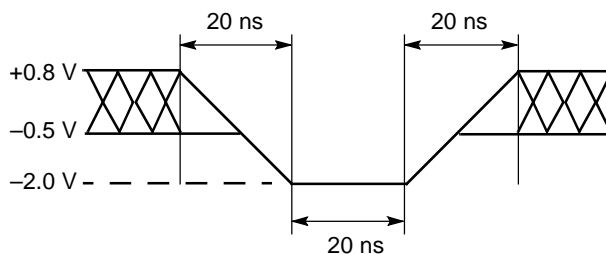


Figure 7. Maximum Negative Overshoot Waveform

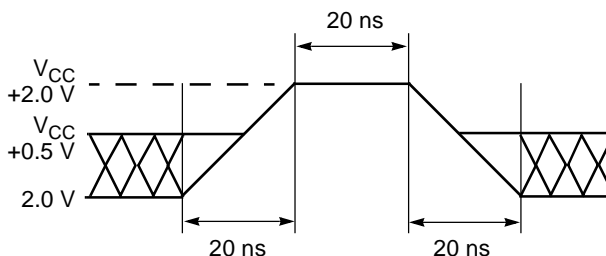


Figure 8. Maximum Positive Overshoot Waveform

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A) 0°C to +70°C

Industrial (I) Devices

Ambient Temperature (T_A) -40°C to +85°C

Extended (E) Devices

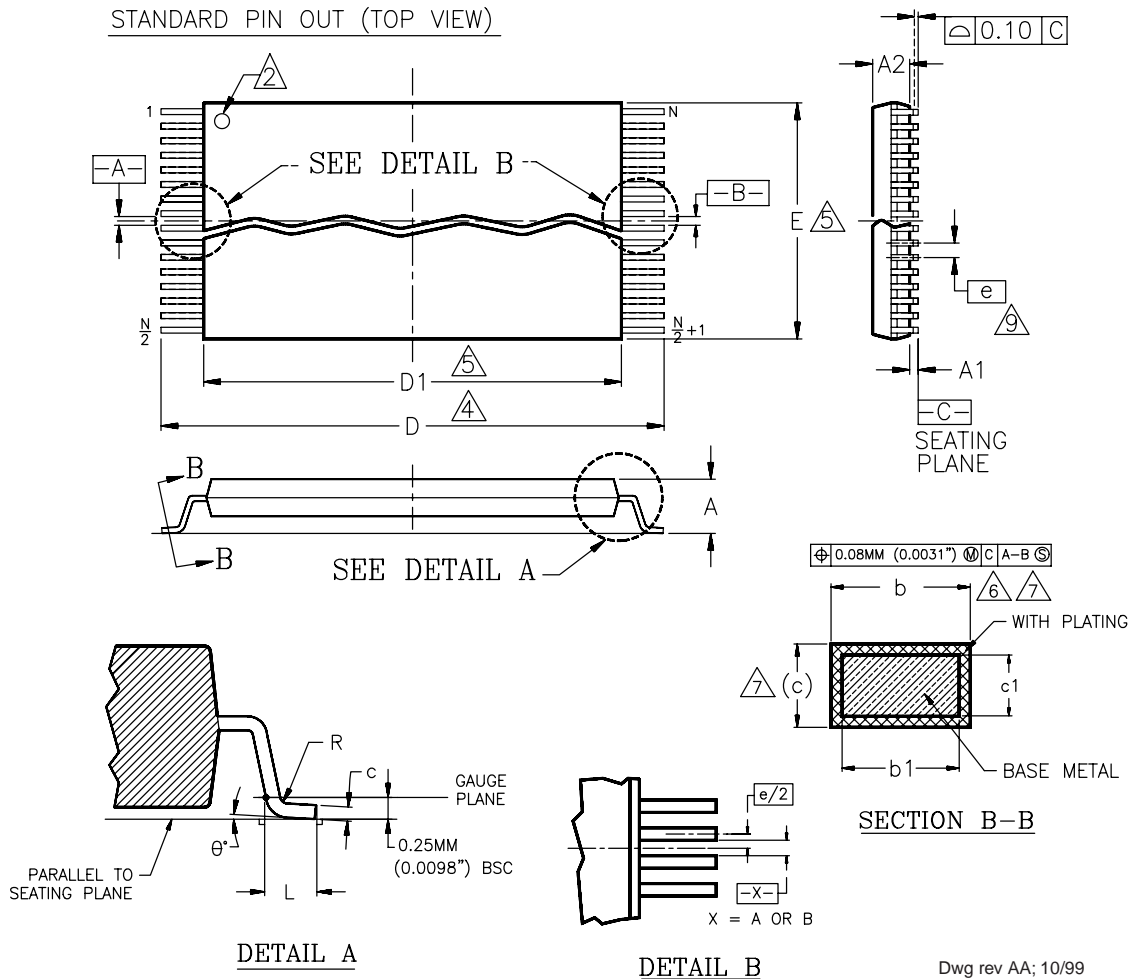
Ambient Temperature (T_A) -55°C to +125°C

V_{CC} Supply Voltages

V_{CC} for all devices 2.7 V to 3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

PHYSICAL DIMENSIONS*
TS 048—48-Pin Standard TSOP



Dwg rev AA; 10/99

Package	TS 48		
Jedec	MO-142 (B) DD		
Symbol	MIN	NOM	MAX
A	—	—	1.20
A1	0.05	—	0.15
A2	0.95	1.00	1.05
b1	0.17	0.20	0.23
b	0.17	0.22	0.27
c1	0.10	—	0.16
c	0.10	—	0.21
D	19.80	20.00	20.20
D1	18.30	18.40	18.50
E	11.90	12.00	12.10
e	0.50 BASIC		
L	0.50	0.60	0.70
theta	0°	3°	5°
R	0.08	—	0.20
N	48		

NOTES:

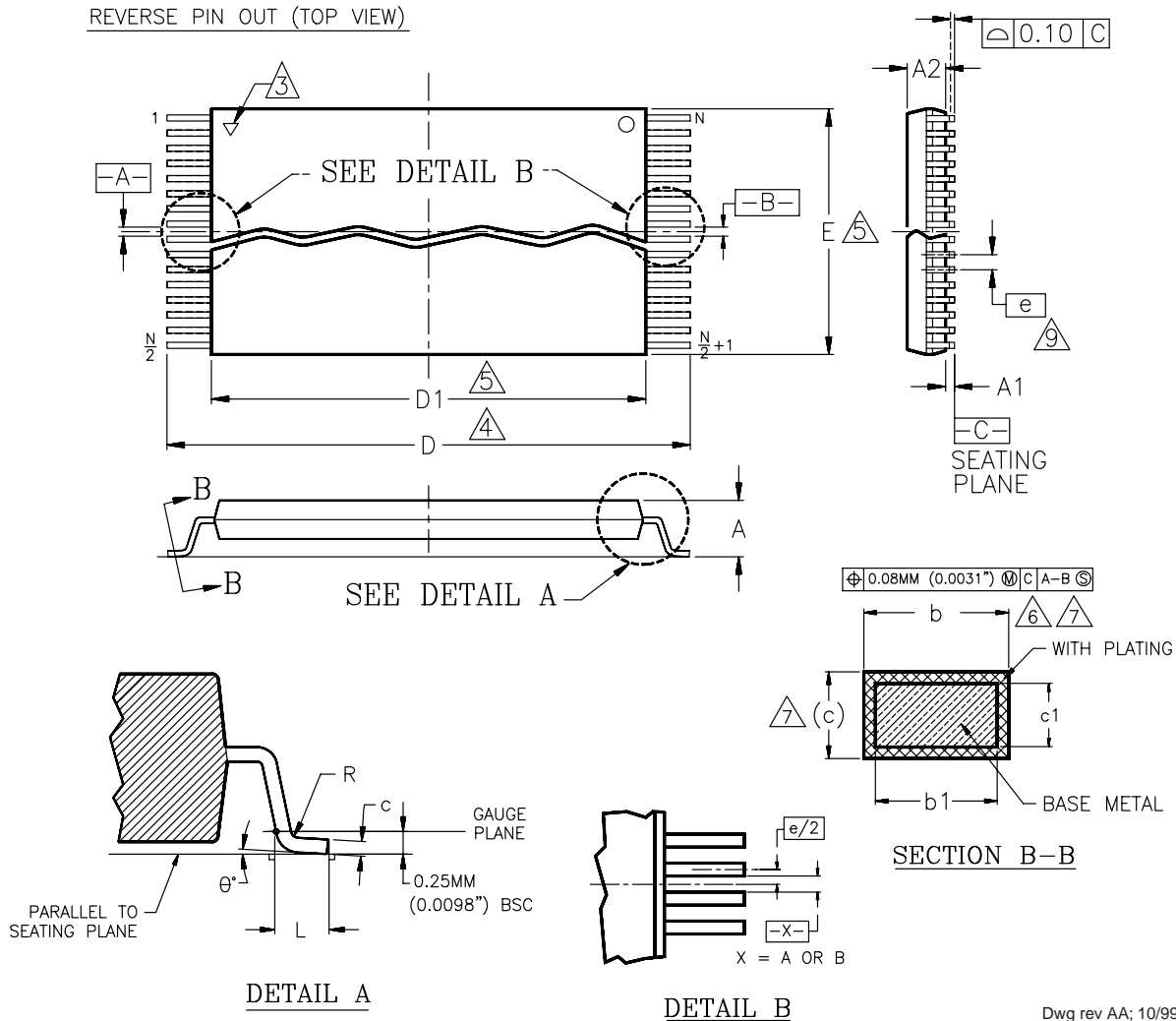
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (mm). (DIMENSIONING AND TOLERANCING CONFORMS TO ANSI Y14.5M-1982)
2. PIN 1 IDENTIFIER FOR STANDARD PIN OUT (DIE UP).
3. PIN 1 IDENTIFIER FOR REVERSE PIN OUT (DIE DOWN): INK OR LASER MARK.
4. TO BE DETERMINED AT THE SEATING PLANE [C]. THE SEATING PLANE IS DEFINED AS THE PLANE OF CONTACT THAT IS MADE WHEN THE PACKAGE LEADS ARE ALLOWED TO REST FREELY ON A FLAT HORIZONTAL SURFACE.
5. DIMENSIONS D1 AND E DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.15mm (0.0059") PER SIDE.
6. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm (0.0031") TOTAL IN EXCESS OF b DIMENSION AT MAX. MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.07mm (0.0028").
7. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm (0.0039") AND 0.25mm (0.0098") FROM THE LEAD TIP.
8. LEAD COPLANARITY SHALL BE WITHIN 0.10mm (0.004") AS MEASURED FROM THE SEATING PLANE.
9. DIMENSION "e" IS MEASURED AT THE CENTERLINE OF THE LEADS.

* For reference only. BSC is an ANSI standard for Basic Space Centering.

PHYSICAL DIMENSIONS

TSR048—48-Pin Reverse TSOP

REVERSE PIN OUT (TOP VIEW)



Dwg rev AA; 10/99

Package	TSR 48		
Jedec	MO-142 (B) DD		
Symbol	MIN	NOM	MAX
A	—	—	1.20
A1	0.05	—	0.15
A2	0.95	1.00	1.05
b1	0.17	0.20	0.23
b	0.17	0.22	0.27
c1	0.10	—	0.16
c	0.10	—	0.21
D	19.80	20.00	20.20
D1	18.30	18.40	18.50
E	11.90	12.00	12.10
e	0.50 BASIC		
L	0.50	0.60	0.70
theta	0°	3°	5°
R	0.08	—	0.20
N	48		

NOTES:

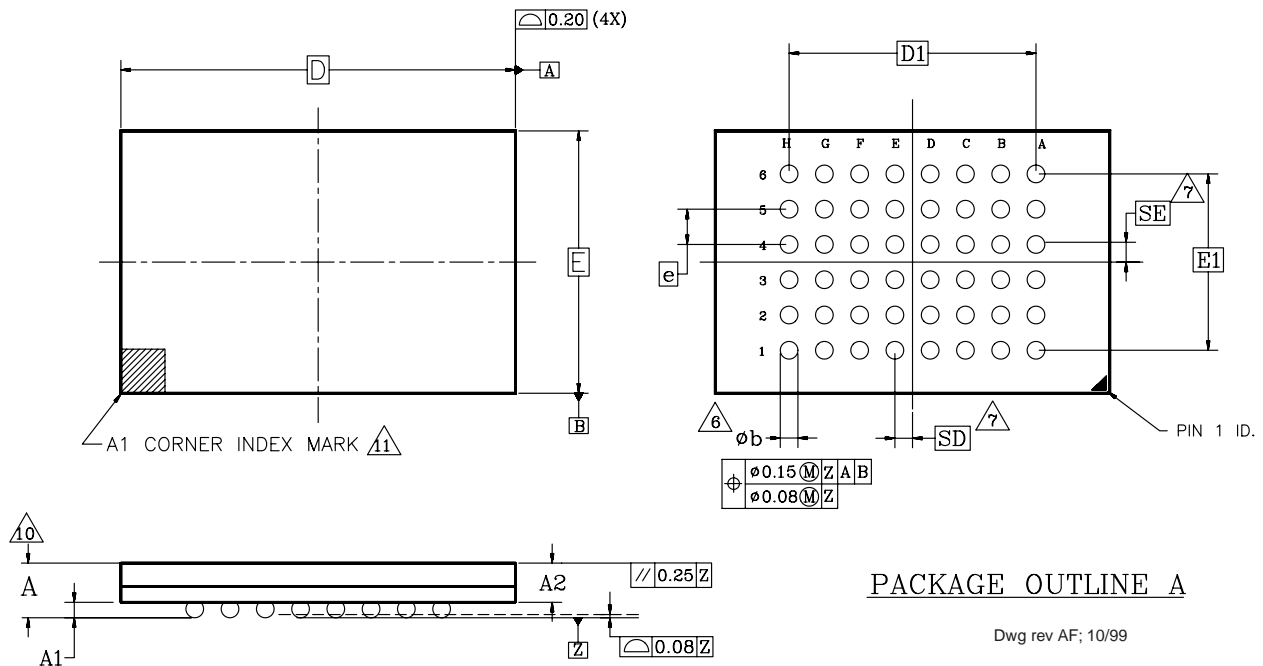
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (mm). (DIMENSIONING AND TOLERANCING CONFORMS TO ANSI Y14.5M-1982)
2. PIN 1 IDENTIFIER FOR STANDARD PIN OUT (DIE UP).
3. PIN 1 IDENTIFIER FOR REVERSE PIN OUT (DIE DOWN): INK OR LASER MARK.
4. TO BE DETERMINED AT THE SEATING PLANE [C], THE SEATING PLANE IS DEFINED AS THE PLANE OF CONTACT THAT IS MADE WHEN THE PACKAGE LEADS ARE ALLOWED TO REST FREELY ON A FLAT HORIZONTAL SURFACE.
5. DIMENSIONS D1 AND E DO NOT INCLUDE MOLD PROTUSION. ALLOWABLE MOLD PROTUSION IS 0.15mm (0.0059") PER SIDE.
6. DIMENSION b DOES NOT INCLUDE DAMBAR PROTUSION. ALLOWABLE DAMBAR PROTUSION SHALL BE 0.08mm (0.0031") TOTAL IN EXCESS OF b DIMENSION AT MAX. MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTUSION AND AN ADJACENT LEAD TO BE 0.07mm (0.0028").
7. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm (0.0039") AND 0.25mm (0.0098") FROM THE LEAD TIP.
8. LEAD COPLANARITY SHALL BE WITHIN 0.10mm (0.004") AS MEASURED FROM THE SEATING PLANE.
9. DIMENSION "e" IS MEASURED AT THE CENTERLINE OF THE LEADS.

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PHYSICAL DIMENSIONS

FBC048—48-Ball Fine-Pitch Ball Grid Array (FBGA)

8 x 9 mm



PACKAGE	FBC 048			NOTE
JEDEC	N/A			
	8.00mmx9.00mm PACKAGE			
SYMBOL	MIN	NOM	MAX	NOTE
A	-	-	1.20	OVERALL THICKNESS
A1	0.20	-	-	BALL HEIGHT
A2	0.84	-	0.94	BODY THICKNESS
D	9.00 BSC			BODY SIZE
E	8.00 BSC			BODY SIZE
D1	5.60 BSC			BALL FOOTPRINT
E1	4.00 BSC			BALL FOOTPRINT
MD	8			ROW MATRIX SIZE D DIRECTION
ME	6			ROW MATRIX SIZE E DIRECTION
N	48			TOTAL BALL COUNT
b	0.25	0.30	0.35	BALL DIAMETER
e	0.80 BSC			BALL PITCH
SD/SE	0.40 BSC			SOLDER BALL PLACEMENT

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- BALL POSITION DESIGNATION PER JESD 95-1, SPP-010.
- [e] REPRESENTS THE SOLDER BALL GRID PITCH.
- SYMBOL "MD" IS THE BALL ROW MATRIX SIZE IN THE "D" DIRECTION. SYMBOL "ME" IS THE BALL COLUMN MATRIX SIZE IN THE "E" DIRECTION. N IS THE MAXIMUM NUMBER OF SOLDER BALLS FOR MATRIX SIZE MD x ME.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER IN A PLANE PARALLEL TO DATUM Z.
- SD AND SE ARE MEASURED WITH RESPECT TO DATUMS A AND B AND DEFINE THE POSITION OF THE CENTER SOLDER BALL IN THE OUTER ROW. WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS IN THE OUTER ROW PARALLEL TO THE D OR E DIMENSION, RESPECTIVELY, SD OR SE = 0.000 WHEN THERE IS AN EVEN NUMBER OF SOLDER BALLS IN THE OUTER ROW, SD OR SE = $e/2$
- "X" IN THE PACKAGE VARIATIONS DENOTES PART IS UNDER QUALIFICATION.
- "+" IN THE PACKAGE DRAWING INDICATE THE THEORETICAL CENTER OF DEPOPULATED BALLS.
- FOR PACKAGE THICKNESS A IS THE CONTROLLING DIMENSION.
- A1 CORNER TO BE IDENTIFIED BY CHAMFER, INK MARK, METALLIZED MARKINGS INDENTION OR OTHER MEANS.